

MULTILAYERED SUBSTRATE FOR SEMICONDUCTOR DEVICE

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ABSTRACT OF THE DISCLOSURE

10 A multilayered substrate for a semiconductor device,  
which has a multilayered substrate body formed of a  
plurality sets of a conductor layer and an insulation  
layer, and having a face for mounting a semiconductor  
element thereon and another face for external connection  
terminals, the face for mounting a semiconductor device  
being provided with pads through which the substrate is  
15 connected to a semiconductor element to be mounted  
thereon, and the face for external connection terminals  
being provided with pads through which the substrate is  
connected to an external electrical circuit, wherein a  
reinforcing sheet is respectively joined to the face for  
20 mounting a semiconductor element thereon and the face for  
external connection terminals of the multilayered  
substrate body.